

WHAT IS CLAIMED IS:

1. A socket for a semiconductor device,  
comprising:

- 5       a socket body having a semiconductor device  
placement section for selectively accommodating one of  
a plurality of semiconductor devices having contour  
dimensions different from each other, to be  
electrically connected to contact terminals;
- 10   a pressing member having an touch portion brought in  
contact with said semiconductor device and pressing  
said semiconductor device toward said contact  
terminals, said pressing member being driven by a  
pressing member driving mechanism in accordance with
- 15   the attachment or detachment of said semiconductor  
device relative to said semiconductor device placement  
section, for holding said semiconductor device in said  
semiconductor device placement section; and
- wherein, when said pressing member driving
- 20   mechanism moves said touch portion of said pressing  
member to be away from said semiconductor device to a  
position in readiness at which said touch portion of  
said pressing member is not interfered with said  
semiconductor device upon the attachment or detachment
- 25   of said semiconductor device, a portion of said  
pressing member is bulged outwardly from an end of  
said socket body via an opening of said socket body.

2. A socket for a semiconductor device,  
comprising:

5 a socket body having a semiconductor device  
placement section for selectively accommodating one of  
a plurality of semiconductor devices having contour  
dimensions different from each other, to be  
electrically connected to contact terminals;

10 a pressing member having an touch portion brought  
in contact with said semiconductor device and pressing  
said semiconductor device toward said contact  
terminals, for holding said semiconductor device in  
said semiconductor device placement section; and

15 a cover member supported by said socket body in a  
movable manner for bring said touch portion of said  
pressing member into contact with or away from said  
semiconductor device in accordance with the attachment  
or detachment of said semiconductor device relative to  
said semiconductor device placement section;

20 wherein, said cover member and said socket body  
have openings, respectively, so that when said cover  
member causes said touch portion of said pressing  
member to be away from said semiconductor device to a  
position in readiness at which said touch portion of  
25 said pressing member is not interfered with said  
semiconductor device, a portion of said pressing  
member is bulged outwardly from an end of said socket

body via the openings.

3. A socket for a semiconductor device as claimed in claim 1, wherein said socket comprising:

5 a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion formed at the proximal end while being deviated in one widthwise direction to be in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; and

15 a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion formed at the proximal end corresponding to said touch portion of said first pressing member while being deviated in said other widthwise direction to be in contact with said semiconductor device so that the semiconductor device is pressed toward said contact terminals.

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4. A socket for a semiconductor device as claimed in claim 1, wherein said socket comprising:

a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals; and

a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; wherein

said second pressing member has a recess for allowing a portion of said first pressing member to enter.

5. A socket for a semiconductor device as claimed in claim 2, wherein said socket comprising:

a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion formed at the proximal end while being deviated in one widthwise

direction to be in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; and

5 a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion formed at the  
10 proximal end corresponding to said touch portion of said first pressing member while being deviated in said other widthwise direction to be in contact with said semiconductor device so that the semiconductor device is pressed toward said contact terminals.

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6. A socket for a semiconductor device as claimed in claim 2, wherein said socket comprising:

a first pressing member for holding said semiconductor device in said semiconductor device  
20 placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals; and

25 a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first

pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion in contact with said semiconductor device so that said semiconductor device  
5 is pressed toward said contact terminals; wherein

said second pressing member has a recess for allowing a portion of said first pressing member to enter.

10 7. A socket for a semiconductor device comprising:

a socket body having a semiconductor device placement section for placing said semiconductor device;

15 contact terminals, each having a contact portion movable to be close to or away from said semiconductor device placement section, for electrically connecting terminals of said semiconductor device to a signal input/output section via said contact portions; and

20 a cover member disposed in said socket body in a movable manner for causing the contact portions of said contact terminals to be close to or away from said semiconductor device placement section; wherein

when said cover member moves close to said socket  
25 body, the contact portions of said contact terminals are away from said semiconductor device placement section and tip ends of engagement end sections of

said contact terminals engaged with said cover member are projected outwardly through an opening of said cover member.

5        8. A socket for a semiconductor device as claimed in claim 7, wherein when said cover member is made to move close to said socket body, the tip end of the engagement end section of said contact terminal is made to move rotationally about a predetermined rotary  
10 center positioned inside said socket body.

9. A socket for a semiconductor device as claimed in claim 7, wherein position of the tip ends of the engagement end sections of said contact terminals  
15 disposed on a opposite sides of said semiconductor device placement section between the both are different in height each other.

10. A socket for a semiconductor device  
20 comprising:

a socket body having a semiconductor device placement section for placing said semiconductor device,

contact terminals, each having a contact portion  
25 movable to be close to or away from said semiconductor device placement section, for electrically connecting terminals of said semiconductor device to a signal

input/output section via said contact portions, and

a lever member disposed in said socket body in a moveably rotational manner for causing the contact portions of said contact terminals to be close to or  
5 away from said semiconductor device placement section, and

a cover member disposed in said socket body in a movable manner for moving rotationally said lever member, wherein

10 when said cover member is made to move close to said socket body, the contact portion of said contact terminal is away from said semiconductor device placement section and one end of said lever member engaged with said cover member is projected outwardly  
15 through an opening of said cover member.

11. A socket for a semiconductor device as claimed in claim 10, wherein the inner peripheral surfaces of said cover members for guiding one ends of  
20 said lever members disposed on opposite sides of said semiconductor device placement section have inclinations different from each other, respectively, and a positions at which an end of the inner peripheral surface of said cover member intersects the  
25 outer peripheral surface of said cover member is different in height in correspondence to the opposite lever members each other.